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December 2010

NC7SV17 TinyLogic[®] ULP-A Single Buffer with Schmitt Trigger Input

Features

- 0.9V to 3.6V V_{CC} Supply Operation
- 3.6V Over-Voltage Tolerant I/Os at Vcc from 0.9V to 3.6V
- Extremely High Speed tpd
 - 1.5ns: Typical for 2.7V to 3.6V V_{CC}
 - 1.8ns: Typical for 2.3V to 2.7V V_{CC}
 - 2.0ns: Typical for 1.65V to 1.95V V_{CC}
 - 3.2ns: Typical for 1.4V to 1.6V V_{CC}
 - 5.9ns: Typical for 1.1V to 1.3V V_{CC}
 - 12.0ns: Typical for 0.9V V_{CC}
- Power-Off High-Impedance Inputs and Outputs
- High Static Drive (I_{OH}/I_{OL})
 - ±24mA at 3.00V V_{CC}
 - ± 18 mA at 2.30V V_{CC}
 - ±6mA at 1.65V V_{CC}
 - $\pm 4mA$ at 1.4V V_{CC}
 - $\pm 2mA$ at 1.1V V_{CC}
 - $\pm 0.1 mA$ at 0.9V V_{CC}
- Uses Proprietary Quiet Series[™] Noise/EMI Reduction Circuitry
- Ultra-Small MicroPak™ Packages
- Ultra-Low Dynamic Power

Description

The NC7SV17 is a single buffer with Schmitt trigger input from Fairchild's Ultra-Low Power (ULP-A) Series of TinyLogic®. ULP-A is ideal for applications that require extreme high speed, high drive, and low power. This product is designed for a wide low-voltage operating range (0.9V to 3.6V $V_{\rm CC}$) and applications that require more drive and speed than the TinyLogic® ULP series, but still offer best-in-class, low-power operation.

The NC7SV17 is uniquely designed for optimized power and speed and is fabricated with an advanced CMOS technology to achieve high-speed operation while maintaining low CMOS power dissipation.

Ordering Information

Part Number	Top Mark	Package	Packing Method
NC7SV17P5X	V17	5-Lead SC70, EIAJ SC-88a, 1.25mm Wide	3000 Units on Tape & Reel
NC7SV17L6X	G5	6-Lead MicroPak™, 1.00mm Wide	5000 Units on Tape & Reel
NC7SV17FHX	G5	6-Lead, MicroPak2™, 1x1mm Body, .35mm Pitch	5000 Units on Tape & Reel

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MicroPak™ and Quiet Series™ are trademarks of Fairchild Semiconductor Corporation.

Battery Life

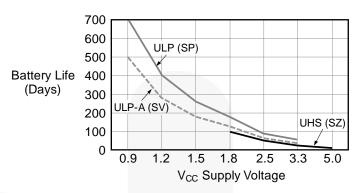


Figure 1. Battery Life vs. Vcc Supply Voltage

Notes:

- TinyLogic® ULP and ULP-A with up to 50% less power consumption can extend battery life significantly. Battery Life = $(V_{battery} \bullet l_{battery} \bullet .9)/(P_{device})/24hrs/day$ where, $P_{device} = (I_{CC} \bullet V_{CC}) + (C_{PD} + C_L) \bullet V_{CC2} \bullet f$.
 Assumes ideal 3.6V Lithium Ion battery with current rating of 900mAH and derated 90% and device frequency at
- 10MHz, with C_L=15pF load.

Connection Diagram



Figure 2. Logic Symbol

Pin Configurations

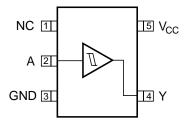


Figure 3. SC70 (Top View)

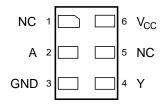


Figure 4. MicroPak™ (Top Through View)

Pin Definitions

Pin # SC70	Pin # MicroPak	Name	Description
1	1	NC	No Connect
2	2	А	Input
3	3	GND	Ground
4	4	Υ	Output
5	6	Vcc	Supply Voltage
	5	NC	No Connect

Function Table

Inputs	Output
Α	Y
L	L
Н	Н

H=HIGH Logic Level L=LOW Logic Level

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Para	Min.	Max.	Unit	
V _{CC}	Supply Voltage		-0.5	4.6	V
V _{IN}	DC Input Voltage		-0.5	4.6	V
\/	DC Output Valtage	HIGH or LOW State ⁽³⁾	-0.5	V _{CC} + 0.5	W
V _{OUT}	DC Output Voltage	V _{CC} =0V	-0.5	4.6	V
I _{IK}	DC Input Diode Current	$V_{IN} < 0V$		-50	mA
	D0.0 / / D1. / O /	V _{OUT} < 0V		-50	
l _{OK}	Iok DC Output Diode Current	$V_{OUT} > V_{CC}$		+50	mA
I _{OH} /I _{OL}	DC Output Source/Sink Curren		±50	mA	
I _{CC} or I _{GND}	DC V _{CC} or Ground Current per	Supply Pin		±50	mA
T _{STG}	Storage Temperature Range		-65	+150	°C
TJ	Junction Temperature Under B	ias	\(+150	°C
TL	Junction Lead Temperature, So	oldering 10 Seconds		+260	°C
		SC70-5		150	
P_{D}	Power Dissipation at +85°C	MicroPak™-6		130	mW
		MicroPak2™-6		120	
ECD	Human Body Model, JEDEC:JE		4000	\/	
ESD	Charge Device Model, JEDEC:JESD22-C101			2000	V

Note:

3. IO absolute maximum rating must be observed.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Conditions	Min.	Max.	Unit	
V _{CC}	Supply Voltage		0.9	3.6	V	
V _{IN}	Input Voltage		0	3.6	V	
Vout	Output Voltage	V _{CC} =0V	0	3.6	V	
VOUT	Output Voltage	HIGH or LOW State	0	V _{cc}	V	
		V _{CC} =3.0V to 3.6V		±24		
	Output Current in L. //	V _{CC} =2.3V to 3.6V		±18		
1 /1		V _{CC} =1.65V to 1.95V		±6		
I _{OH} /I _{OL}	Output Current in I _{OH} /I _{OL}	V _{CC} =1.4V to 1.6V		±4	mA	
		V _{CC} =1.1V to 1.3V		±2		
		V _{CC} =0.9V		±0.1		
T_A	Operating Temperature, Free Air		-40	+85	°C	
Δt/ΔV	Minimum Input Edge Rate	V _{IN} =0.8V to 2.0, V _{CC} =3.0V		10	ns/V	
		SC70-5		425		
θ_{JA}	Thermal Resistance	MicroPak™-6		500	°C/W	
		MicroPak2™-6		560		

Note:

4. Unused inputs must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

Symbol Parameter	Danamatan	v	O a maliti a ma	T _A =25	5°C	T _A =-40 to	85°C	11
	V _{cc}	Conditions	Min.	Max.	Min.	Max.	Units	
	0.90		0.30	0.70	0.30	0.70		
		1.10		0.40	1.00	0.40	1.00	
	Positive	1.40		0.50	1.40	0.50	1.40	.,
V_P	Threshold Voltage	1.65		0.70	1.50	0.70	1.50	V
		2.30		1.00	1.80	1.00	1.80	
		2.70		1.50	2.20	1.50	2.20	
		0.90		0.10	0.60	0.10	0.60	
		1.10		0.15	0.70	0.15	0.70	
V	Negative Threshold	1.40		0.20	0.80	0.20	0.80	\/
V_N	Voltage	1.65		0.25	0.90	0.25	0.90	V
		2.30		0.40	1.15	0.40	1.15	
		2.70		0.60	1.50	0.60	1.50	
		0.90		0.07	0.50	0.07	0.50	
		1.10		0.08	0.60	0.08	0.60	
	Hysteresis	1.40		0.09	0.80	0.09	0.80	V
V _H	Voltage	1.65		0.15	1.00	0.15	1.00	V
		2.30		0.25	1.10	0.25	1.10	
	/	2.70		0.60	1.20	0.60	1.20	
		0.90		V _{CC} -0.1		V _{CC} -0.1		
		$1.10 \leq V_{CC} \leq 1.30$		V _{CC} -0.1		V _{CC} -0.1		
		$1.40 \le V_{CC} \le 1.60$	100 4	V _{CC} -0.2		V _{CC} -0.2		
		$1.65 \le V_{CC} \le 1.95$	Ι _{ΟΗ} =-100μΑ	V _{CC} -0.2		V _{CC} -0.2		
		$2.30 \leq V_{CC} \leq 2.70$		V _{CC} -0.2		V _{CC} -0.2		
		$2.70 \le V_{CC} \le 3.60$		V _{CC} -0.2		V _{CC} -0.2		
		1.10 ≤ V _{CC} ≤ 1.30	I _{OH} =-2mA	.75 x V _{CC}		.75 x V _{CC}		
V_{OH}	HIGH Level	1.40 ≤ V _{CC} ≤ 1.60	I _{OH} =-4mA	.75 x V _{CC}		.75 x V _{CC}		V
	Output Voltage	1.65 ≤ V _{CC} ≤ 1.95	I _{OH} =-6mA	1.25		1.25		
		$2.30 \le V_{CC} \le 2.70$		2.0		2.0		
		$2.30 \le V_{CC} \le 2.70$	I _{OH} =-12mA	1.8		1.8		1
		2.70≤ V _{CC} ≤ 3.60		2.2		2.2		
		$2.30 \le V_{CC} \le 2.70$	I _{OH} =-18mA	1.7		1.7		
		$2.70 \le V_{CC} \le 3.60$	3.1	2.4		2.4		1
		$2.70 \le V_{CC} \le 3.60$	I _{OH} =-24mA	2.2		2.2		

Continued on following page...

DC Electrical Characteristics (Continued)

0	Barrara atau	.,,	O a madistica a a	T _A =2	25°C	T _A =-40	to 85°C	1111-
Symbol	Parameter	V _{CC}	Conditions	Min.	Max.	Min.	Max.	Units
		0.90			0.10		0.10	
		$1.10 \leq V_{CC} \leq 1.30$			0.10		0.10	
		$1.40 \le V_{CC} \le 1.60$	1.004		0.20		0.20	
		$1.65 \leq V_{CC} \leq 1.95$	I _{OL} =100μA		0.20		0.20	
		$2.30 \leq V_{CC} \leq 2.70$			0.20		0.20	
		$2.70 \leq V_{CC} \leq 3.60$			0.20		0.20	
	LOW Level	$1.10 \le V_{CC} \le 1.30$	I _{OL} =2mA		0.25 x V _{CC}		0.25 x V _{CC}	V
V _{OL}	Output Voltage	$1.40 \le V_{CC} \le 1.60$	I _{OL} =4mA		0.25 x V _{CC}		0.25 x V _{CC}	V
		$1.65 \le V_{CC} \le 1.95$	I _{OL} =6mA		0.30		0.30	
		$2.30 \leq V_{CC} \leq 2.70$	Ι 10m Λ		0.40		0.40	
		$2.70 \leq V_{CC} \leq 3.60$	I _{OL} =12mA		0.40		0.40	
		2.30≤ V _{CC} ≤ 2.70	Ι 10 m Λ		0.60		0.60	
		$2.70 \leq V_{CC} \leq 3.60$	I _{OL} =18mA		0.40		0.40	
		$2.70 \leq V_{CC} \leq 3.60$	I _{OL} =24mA		0.55		0.55	
I _{IN}	Input Leakage Current	0.90 to 3.60	$0 \leq V_{IN} \leq 3.60$		±0.1		±0.5	μA
I _{OFF}	Power Off Leakage Current	0	$0 \le (V_{IN}, v_O) \le 3.60$		0.5		0.5	μΑ
	Quiescent	0.00 to 2.60	V _{IN} =V _{CC} , or GND		0.9		0.9	
Icc	0.90 to 3.60	$V_{CC} \leq V_{IN} \leq 3.6 V$				±0.9	μA	

AC Electrical Characteristics

Cumb al	Davamatav	W	Canditiana		T _A =25°(2	T _A =-40	to 85°C	l linita	Figure
Symbol Parameter	V _{cc}	Conditions	Min.	Тур.	Max.	Min.	Max.	Units	Figure	
	0.90	$C_L=15pF$, $R_L=1M\Omega$		12						
		$1.10 \le V_{CC} \le 1.30$	C _L =15pF,	2.0	5.9	10.0	1.0	14.9		
t _{PHL} , t _{PLH}	Propagation	$1.40 \leq V_{CC} \leq 1.60$	$R_L=2k\Omega$	1.0	3.2	6.1	0.9	7.0	ns	Figure 5 Figure 6
	Delay	$1.65 \leq V_{CC} \leq 1.95$	C _L =30pF, R _L =500O	1.0	2.0	5.2	0.7	6.2		rigule 6
		$2.30 \leq V_{CC} \leq 2.70$		$C_L=30pF$, $R_1=500\Omega$	0.8	1.8	3.7	0.6	4.4	
		$2.70 \leq V_{CC} \leq 3.60$	11,00021	0.7	1.5	3.3	0.5	3.8		
C _{IN}	Input Capacitance	0			2				pF	\mathcal{S}
C _{PD}	Power Dissipation Capacitance	0.90 to 3.60	V _{IN} =0V or V _{CC} , f=10MHz		10				pF	

AC Loadings and Waveforms

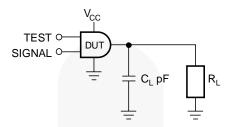


Figure 5. AC Test Circuit

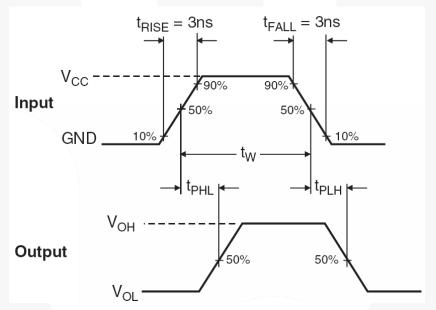


Figure 6. AC Waveforms

Symbol			V	cc		
Symbol	3.3V ± 0.3V	2.5V ± 0.2V	1.8V ± 0.15V	1.5V ± 0.1V	1.2V ± 0.1V	0.9V
V _{mi}	1.5V	V _{CC} /2				
V _{mo}	1.5V	V _{CC} /2				

Physical Dimensions

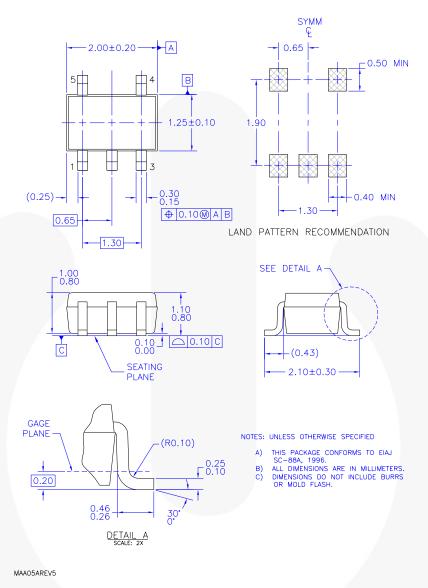


Figure 7. 5-Lead, SC70, EIAJ SC-88a, 1.25mm Wide

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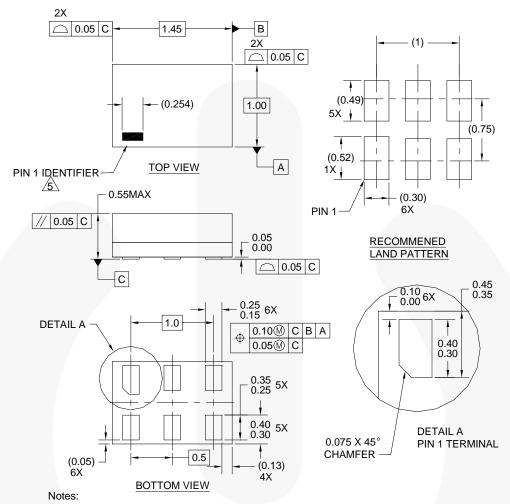
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Tape and Reel Specification

Please visit Fairchild Semiconductor's online packaging area for the most recent tape and reel specifications: http://www.fairchildsemi.com/products/analog/pdf/sc70-5 tr.pdf.

Package Designator Tape Section		Cavity Number	Cavity Status	Cover Type Status
	Leader (Start End)	125 (Typical)	Empty	Sealed
P5X	Carrier	3000	Filled	Sealed
	Trailer (Hub End)	75 (Typical)	Empty	Sealed

Physical Dimensions



- 1. CONFORMS TO JEDEC STANDARD M0-252 VARIATION UAAD
- 2. DIMENSIONS ARE IN MILLIMETERS
- 3. DRAWING CONFORMS TO ASME Y14.5M-1994
- 4. FILENAME AND REVISION: MAC06AREV4
- 5. PIN ONE IDENTIFIER IS 2X LENGTH OF ANY

OTHER LINE IN THE MARK CODE LAYOUT.

Figure 8. 6-Lead, MicroPak™, 1.0mm Wide

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Tape and Reel Specification

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Package Designator	Tape Section	Cavity Number	Cavity Status	Cover Type Status
	Leader (Start End)	125 (Typical)	Empty	Sealed
L6X	Carrier	5000	Filled	Sealed
	Trailer (Hub End)	75 (Typical)	Empty	Sealed

Physical Dimensions 0.89 ○ 0.05 C 1.00 В 2X 5X 0.40 PIN 1 0.66 MIN 250uM 1.00 1X 0.45 6X 0.19 □ | 0.05 | C | **TOP VIEW** RECOMMENDED LAND PATTERN 2X FOR SPACE CONSTRAINED PCB // 0.05 C 0.55MAX С 5X 0.52 SIDE VIEW 0.73 (0.08) 4X -0.09 6X **DETAIL** A 0.19 - 0.20 6X ALTERNATIVE LAND PATTERN FOR UNIVERSAL APPLICATION (0.05) 6X5X 0.35 0.25 0.60 0.10(M) C B A \oplus 0.35 0.40 (0.08).05 C 0.30 4X **BOTTOM VIEW** NOTES: A. COMPLIES TO JEDEC MO-252 STANDARD B. DIMENSIONS ARE IN MILLIMETERS. C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994 0.075X45° **DETAIL A** D. LANDPATTERN RECOMMENDATION IS BASED ON FSC CHAMFER

Figure 9. 6-Lead, MicroPak2, 1x1mm Body, .35mm Pitch

PIN 1 LEAD SCALE: 2X

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E. DRAWING FILENAME AND REVISION: MGF06AREV3

Tape and Reel Specification

Please visit Fairchild Semiconductor's online packaging area for the most recent tape and reel specifications: http://www.fairchildsemi.com/packaging/MicroPAK2_6L_tr.pdf.

Package Designator	Package Designator Tape Section		Cavity Status	Cover Type Status
	Leader (Start End)	125 (Typical)	Empty	Sealed
FHX	Carrier	5000	Filled	Sealed
	Trailer (Hub End)	75 (Typical)	Empty	Sealed





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MillerDrive™

MotionMa×™

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SuperSOT™8 SupreMOS® SvncFET** Sync-Lock™ SYSTEM GENERAL®

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 $\mu_{\scriptscriptstyle{\mathsf{Ser}}}$ UHC Ultra FRFET™ UniFET™ VCX™ VisualMax™ XSTM

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Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

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